



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD068P03L3 G		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA000511346						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		314.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.479	0.79	0.79	7890	7890
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		456	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	copper	7440-50-8	143.098	45.53	45.59	455437	456030
wire	non noble metal	aluminium	7429-90-5	2.536	0.81	0.81	8070	8070
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.969	0.63		6265	
	plastics	brominated resin	-	2.109	0.67		6713	
	organic material	carbon black	1333-86-4	2.250	0.72		7160	
	plastics	epoxy resin	-	18.983	6.04		60416	
	inorganic material	silicondioxide	60676-86-0	115.301	36.70	44.76	366969	447523
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11903	11903
plating	non noble metal	nickel	7440-02-0	0.086	0.03		275	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	276
solder	noble metal	silver	7440-22-4	0.056	0.02		180	
	non noble metal	tin	7440-31-5	0.045	0.01		144	
	non noble metal	lead	7439-92-1	2.158	0.69	0.72	6869	7193
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.10	6.11	61036	61115
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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